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TLE4998S3
TLE4998S4

Programmable Linear Hall Sensor

Sensors

Never stop thinking.

Edition 2008-07

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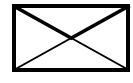

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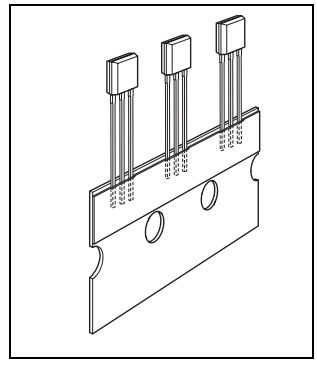
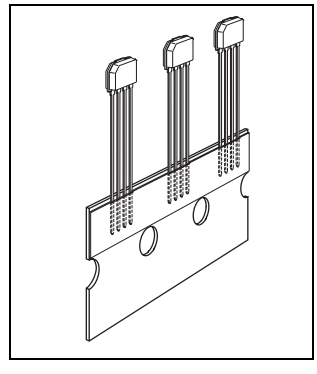
Programmable Linear Hall Sensor **TLE4998S3**

TLE4998S4

1 Overview

1.1 Features





- Single Edge Nibble Transmission (SENT) open-drain output signal (SAE J2716)
- 20-bit Digital Signal Processing (DSP)
- Digital temperature compensation
- 16-bit overall resolution
- Operates within automotive temperature range
- Low drift of output signal over temperature and lifetime
- Programmable parameters stored in EEPROM with single-bit error correction:
  - SENT unit time
  - Magnetic range and sensitivity (gain), polarity of the output slope
  - Offset
  - Bandwidth
  - Clamping levels
  - Customer temperature compensation coefficients
  - Memory lock
- Re-programmable until memory lock
- Single supply voltage 4.5 - 5.5 V (4.1 - 16 V in extended range)
- Operation between -200 mT and +200 mT within three ranges
- Reverse-polarity and overvoltage protection for all pins
- Output short-circuit protection
- On-board diagnostics (overvoltage, EEPROM error, start up)
- Output of internal magnetic field values and temperature
- Programming and operation of multiple sensors with common power supply
- Two-point calibration of magnetic transfer function without iteration steps
- High immunity against mechanical stress, EMC, ESD

Type	Marking	Ordering Code	Package
TLE4998S3	4998S3	SP412108	PG-SSO-3-10
TLE4998S4	4998S4	SP412110	PG-SSO-4-1

1.2 Target Applications

- Robust replacement of potentiometers
  - No mechanical abrasion
  - Resistant to humidity, temperature, pollution and vibration
- Linear and angular position sensing in automotive applications such as pedal position, suspension control, throttle position, headlight levelling, and steering torque sensing
- Sensing of high current for battery management, motor control, and electronic fuses

1.3 Pin Configuration

Figure 1 and **Figure 2** show the location of the Hall element in the chip and the distance between Hall probe and the surface of the package.

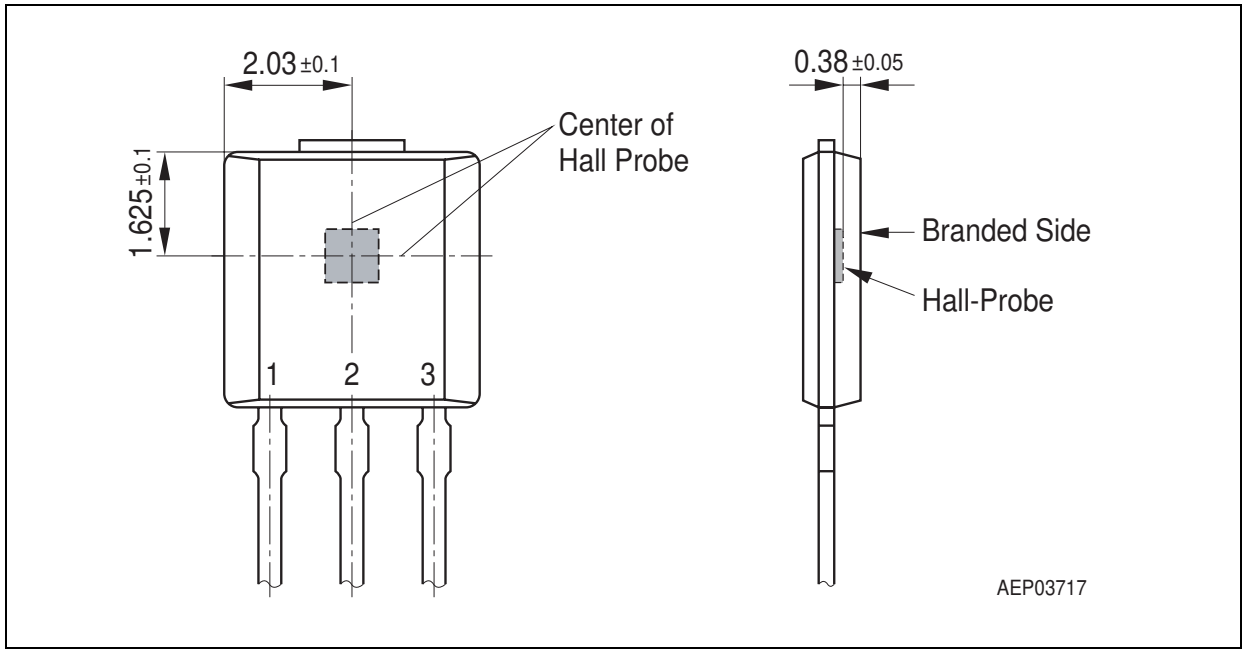


Figure 1 TLE4998S3 Pin Configuration and Hall Cell Location

Table 1 TLE4998S3 Pin Definitions and Functions

Pin No.	Symbol	Function
1	*VDD*	Supply voltage / programming interface
2	*GND*	Ground
3	*OUT*	Output / programming interface

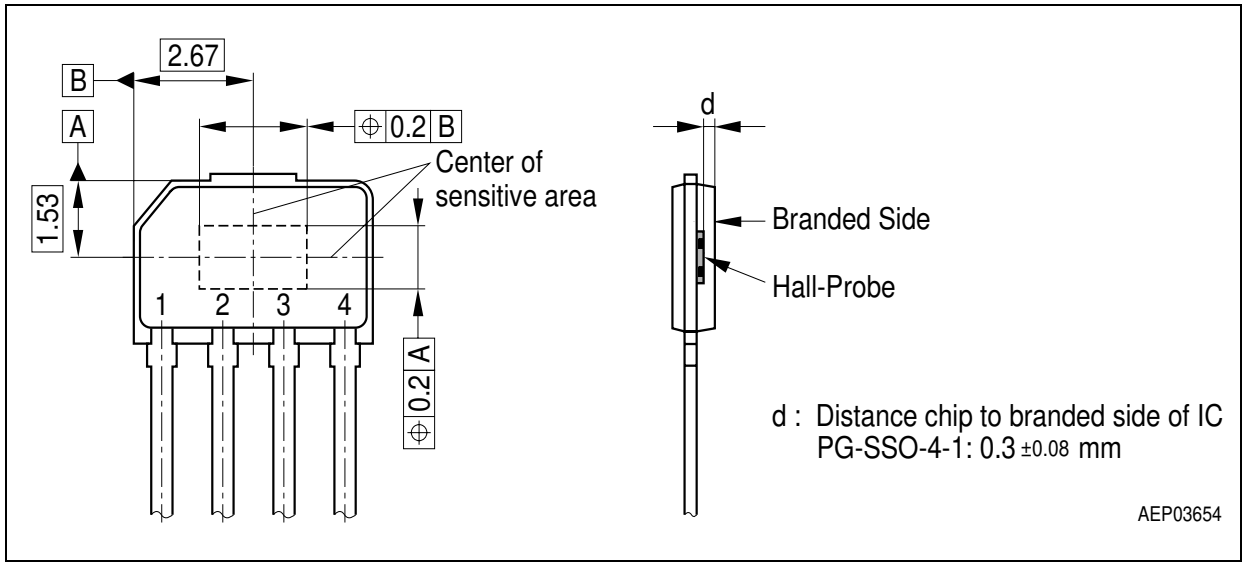


Figure 2 TLE4998S4 Pin Configuration and Hall Cell Location

Table 2 TLE4998S4 Pin Definitions and Functions

Pin No.	Symbol	Function
1	*TST*	Test pin (connection to *GND* is recommended)
2	*VDD*	Supply voltage / programming interface
3	*GND*	Ground
4	*OUT*	Output / programming interface

2 General

2.1 Block Diagram

Figure 3 is a simplified block diagram.

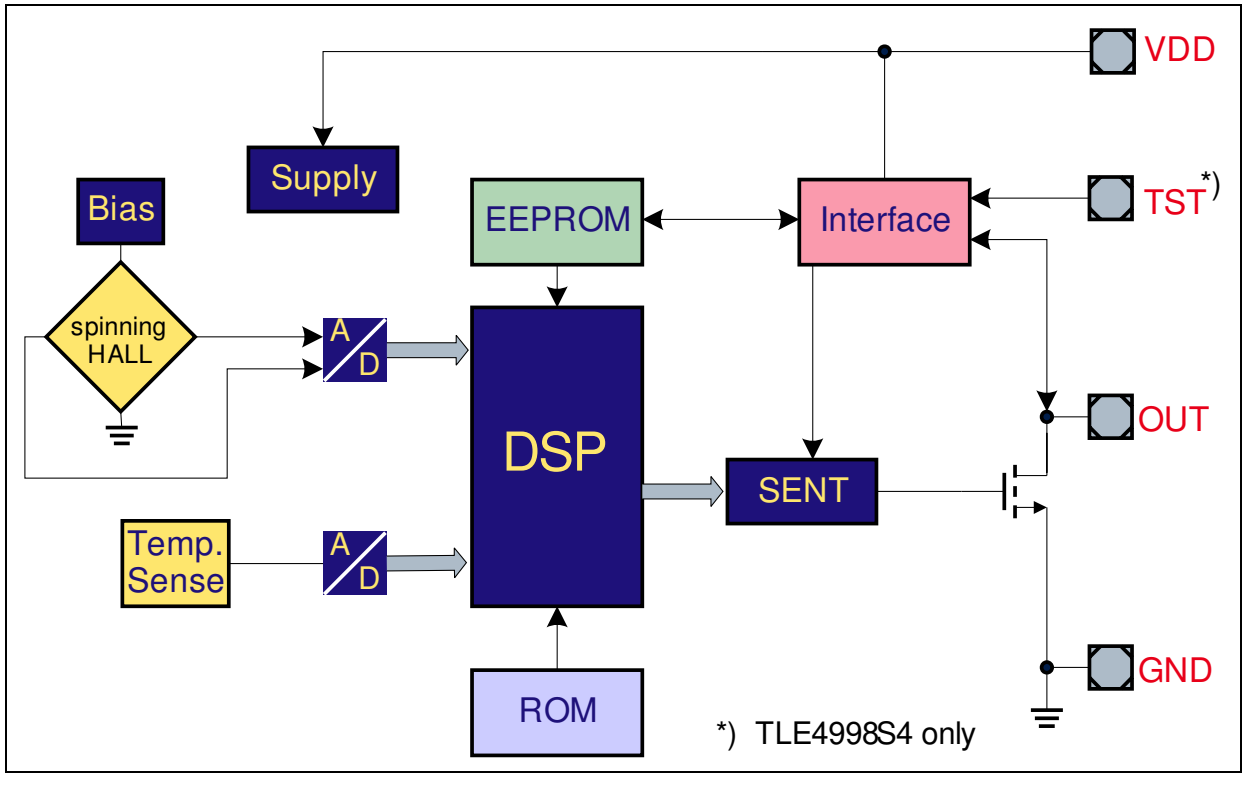


Figure 3 Block Diagram (TLE4998S4)

2.2 Functional Description

The linear Hall IC TLE4998S has been designed specifically to meet the requirements of highly accurate rotation and position detection, as well as for current measurement applications.

The sensor provides a digital SENT signal based on the SAE J2716 standard, which consists of a sequence of pulses. Each transmission has a constant number of nibbles containing the Hall value, the temperature, and status information of the sensor.

The output stage is an open-drain driver pulling the output pin to low only. Therefore, the high level needs to be obtained by an external pull-up resistor. This output type has the advantage that the receiver may use an even lower supply voltage (e.g. 3.3 V). In this case the pull-up resistor must be connected to the given receiver supply.

The IC is produced in BiCMOS technology with high voltage capability, and it also has reverse-polarity protection.

Digital signal processing using a 16-bit DSP architecture together with digital temperature compensation guarantee excellent long-time stability compared to analog compensation methods.

While the overall resolution is 16 bits, some internal stages work with resolutions up to 20 bits.

2.3 Principle of Operation

- A magnetic flux is measured by a Hall-effect cell
- The output signal from the Hall-effect cell is converted from analog to digital
- The chopped Hall-effect cell and continuous-time A/D conversion ensure a very low and stable magnetic offset
- A programmable low-pass filter to reduce noise
- The temperature is measured and A/D converted, too
- Temperature compensation is done digitally using a second-order function
- Digital processing of output value is based on zero field and sensitivity value
- The output value range can be clamped by digital limiters
- The final output value is represented by the data nibbles of the SENT protocol

2.4 Transfer Functions

The examples in **Figure 4** show how different magnetic field ranges can be mapped to the desired output value ranges.

- Polarity Mode:
  - **Bipolar**: Magnetic fields can be measured in both orientations. The limit points do not necessarily have to be symmetrical around the zero field point
  - **Unipolar**: Only north- or south-oriented magnetic fields are measured
- Inversion: The gain can be set to both positive and negative values

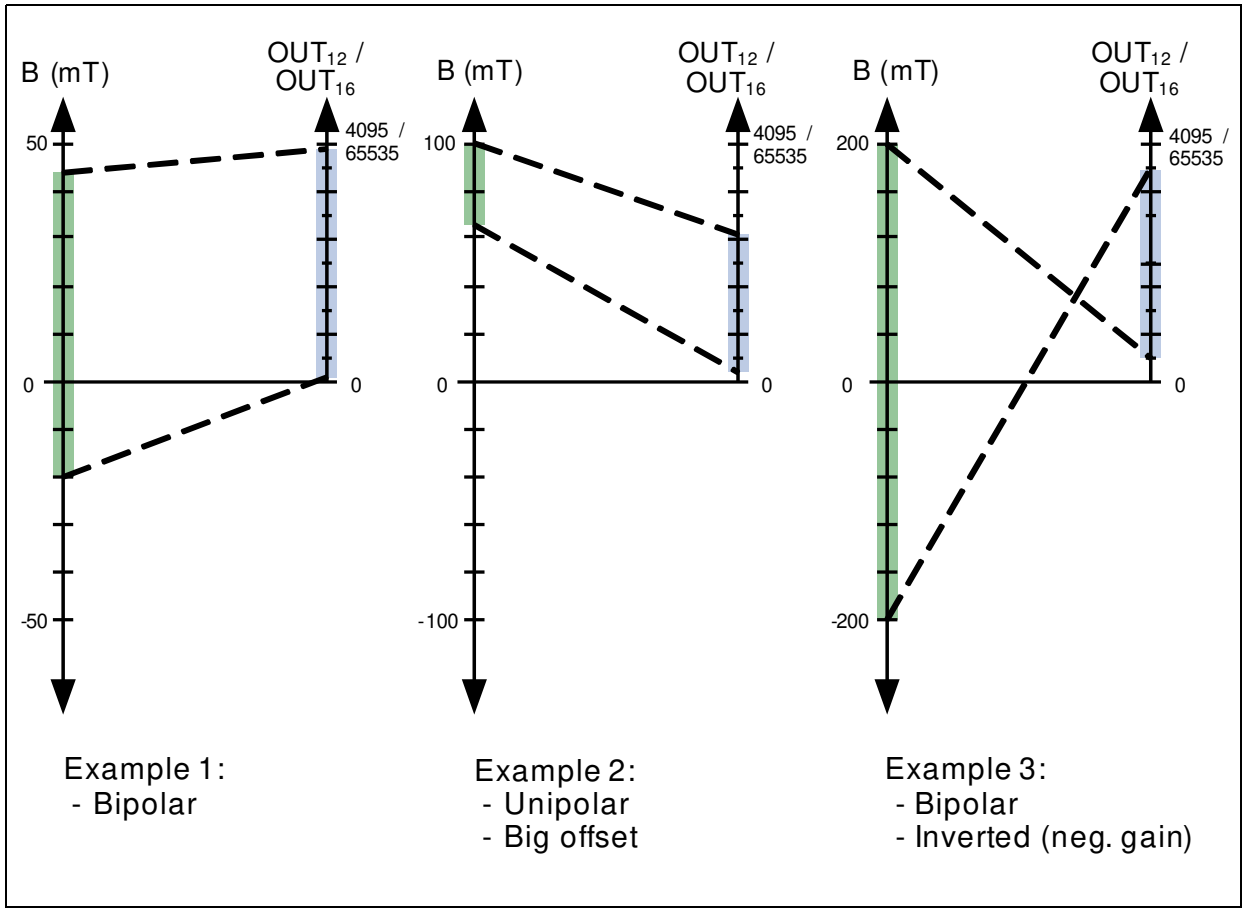


Figure 4 Examples of Operation

3 Maximum Ratings

Table 3 Absolute Maximum Ratings

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Storage temperature	T_{ST}	- 40	150	°C	
Junction temperature	T_J	- 40	170[1)]	°C	
Voltage on V_{DD} pin with respect to ground	V_{DD}	-18	18	V	[2)]
Supply current @ overvoltage V_{DD} max.	I_{DDov}	-	15	mA	
Reverse supply current @ V_{DD} min.	I_{DDrev}	-1	0	mA	
Voltage on output pin with respect to ground	V_{OUT}	-1[3)]	18[4)]	V	
Magnetic field	B_{MAX}	-	unlimited	T	
ESD protection	V_{ESD}	-	4.0	kV	According HBM JESD22-A114-B [5)]

1) For limited time of 96 h. Depends on customer temperature lifetime cycles. Please ask for support by Infineon

2) Higher voltage stress than absolute maximum rating, e.g. 150% in latch-up tests is not applicable. In such cases, $R_{series} \geq 100\ \Omega$ for current limitation is required

3) I_{DD} can exceed 10 mA when the voltage on OUT is pulled below -1 V (-5 V at room temperature)

4) V_{DD} = 5 V, open drain permanent low, for max. 10 minutes

5) 100 pF and 1.5 kΩ

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

4 Operating Range

The following operating conditions must not be exceeded in order to ensure correct operation of the TLE4998S. All parameters specified in the following sections refer to these operating conditions, unless otherwise indicated.

Table 4 Operating Range

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Supply voltage	V_{DD}	4.5	5.5	V	
		4.1[1]	16[2]	V	Extended range
Output pull-up voltage[3]	$V_{pull-up}$	-	18	V	
Load resistance[3]	R_L	1	-	kΩ	
Output current[3]	I_{OUT}	0	5	mA	
Load capacitance[3]	C_L	1	8	nF	
Junction temperature	T_J	- 40	125 150[4]	°C	For 5000 h For 1000 h not additive

1) For reduced output accuracy

2) For supply voltages > 12 V, a series resistance $R_{series} \geq 100\ \Omega$ is recommended

3) Required output protocol characteristics depend on these parameters, R_L must be according to max. output current

4) For reduced magnetic accuracy; extended limits are taken for characteristics

Note: Keeping signal levels within the limits specified in this table ensures operation without overload conditions.

5 Electrical, Thermal, and Magnetic Parameters

Table 5 Electrical Characteristics

Parameter	Symbol	Limit Values			Unit	Notes
		min.	typ.	max.		
SENT transmission time	t_{SENT}	-	-	1	ms	1)
Supply current	I_{DD}	3	6	8	mA	
Output current @ OUT shorted to supply lines	I_{OUTsh}	-	95	-	mA	V_{OUT} = 5 V, max. 10 minutes
Thermal resistance TLE4998S3	R_{thJA}	-	219	-	K/W	Junction to air
	R_{thJC}	-	47	-	K/W	Junction to case
Thermal resistance TLE4998S4	R_{thJA}	-	240	-	K/W	Junction to air
	R_{thJC}	-	41	-	K/W	Junction to case
Power-on time2)	t_{Pon}	-	0.7 15	2 20	ms	≤ ± 5% target out value ≤ ± 1% target out value
Power-on reset level	V_{DDpon}	-	3.6	4	V	
Output impedance	Z_{OUT}	19	30	44	kΩ	3)
Output fall time	t_{fall}	2	-	4	µs	V_{OUT} 4.5 V to 0.5 V 4)
Output rise time	t_{rise}	-	20	-	µs	V_{OUT} 0.5 V to 4.5 V 4)5)
Output low time	t_{low}	-	9	-	µs	SENT edge generation
Output min. high time	$t_{HIGH\ min}$	-	36	-	µs	SENT “0” nibble
Output max. high time	$t_{HIGH\ max}$	-	168	-	µs	SENT synchron. frame
Output low saturation voltage	V_{OUTsat}	-	0.3 0.2	0.6 0.4	V	$I_{OUTsink}$ = 5 mA $I_{OUTsink}$ = 2.2 mA
Output noise (rms)	OUT_{noise}	-	1	2.5	LSB_{12}	6)

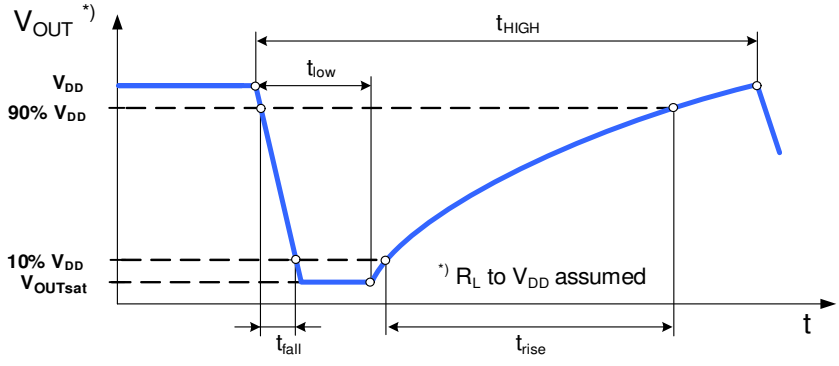
1) Transmission time depends on the data values being sent and on int. RC oscillator freq. variation of +/- 20%

2) Response time to set up output data at power on when a constant field is applied. The first value given has a ± 5% error, the second value has a ± 1% error. Measured with 640-Hz low-pass filter

3) VDD = 5V, open drain high state, voltage on OUT pin typ. 84% of VDD

4) For V_{DD} = 5 V, R_L = 2.2 kΩ, C_L = 4.7 nF

5) Depends on external R_L and C_L



6) Range 100 mT, Gain 2.23, internal LP filter 244 Hz, B = 0 mT, T = 25 °C

Calculation of the Junction Temperature

The internal power dissipation P_{TOT} of the sensor increases the chip junction temperature above the ambient temperature.

The power multiplied by the total thermal resistance R_{thJA} (Junction to Ambient) added to T_A leads to the final junction temperature. R_{thJA} is the sum of the addition of the two components, *Junction to Case* and *Case to Ambient*.

$$R_{thJA} = R_{thJC} + R_{thCA}$$
$$T_J = T_A + \Delta T$$
$$\Delta T = R_{thJA} \times P_{TOT} = R_{thJA} \times (V_{DD} \times I_{DD} + V_{OUT} \times I_{OUT}) \quad I_{DD}, I_{OUT} > 0, \text{if direction is into IC}$$

Example (assuming no load on Vout and TLE4998S4 type):

- V_{DD} = 5 V
- I_{DD} = 8 mA
- ΔT = 240 [K/W] x (5 [V] x 0.008 [A] + 0 [VA]) = 9.6 K

For moulded sensors, the calculation with R_{thJC} is more adequate.

Magnetic Parameters

Table 6 Magnetic Characteristics

Parameter	Symbol	Limit Values			Unit	Notes
		min.	typ.	max.		
Sensitivity	S 1)	± 8.2	-	± 245	LSB_{12}/ mT	Programmable 2)3)
Temperature coefficient of sensitivity	TC	-150	0	150	ppm/ °C	4) See **Figure 5**
Magnetic field range	MFR	± 50	± 100 5)	± 200	mT	Programmable 6)
Integral nonlinearity	INL	- 0.1	-	0.1	%MFR	7)9)
Magnetic offset	B_{OS}	- 400	0	400	µT	8)9)
Magnetic offset drift	ΔB_{OS}	- 5	-	5	µT / °C	Error band 9)
Magnetic hysteresis	B_{HYS}	0	-	10	µT	10)

1) Defined as ΔOUT / ΔB

2) Programmable in steps of 0.024%

3) @ V_{DD} = 5 V and T_J = 25 °C

4) For any 1st and 2nd order polynomial, coefficient within definition in Chapter 8.

5) This range is also used for temperature and offset pre-calibration of the IC

6) Depending on offset and gain settings, the output may already be saturated at lower fields

7) Gain setup is 1.0

8) In operating temperature range and over lifetime

9) Measured at ± 100 mT range

10) Measured in 100 mT range, Gain = 1, room temperature

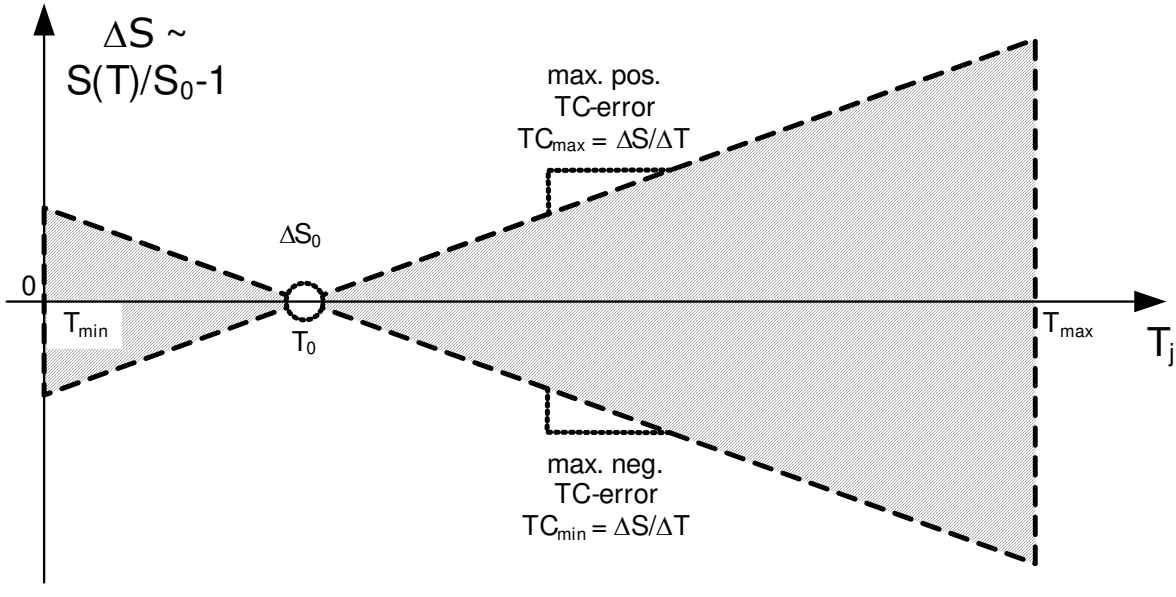


Figure 5 Drift of Temperature Coefficient

6 Signal Processing

The signal flow diagram in **Figure 6** shows the signal path and data-processing algorithm.

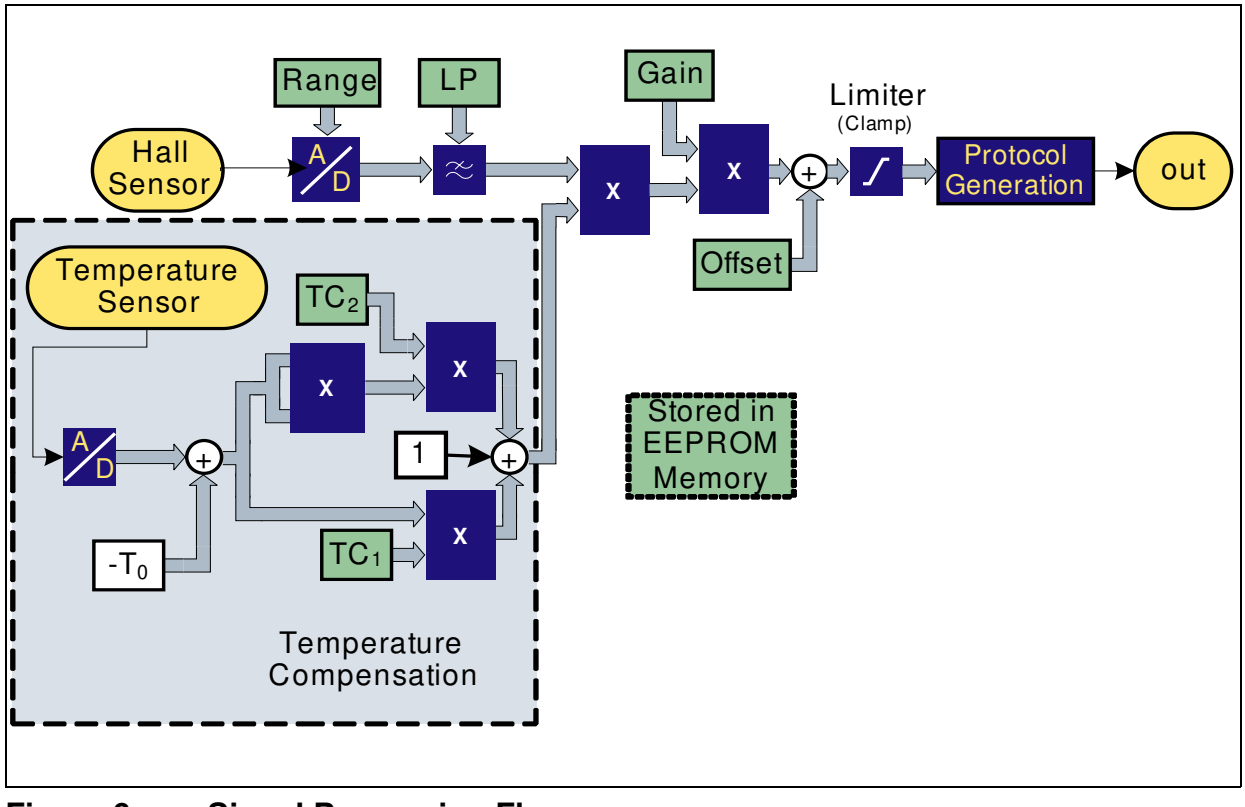


Figure 6 Signal Processing Flow

Magnetic Field Path

- The analog output signal of the chopped Hall-effect cell is converted to a digital signal in the continuous-time A/D converter. The range of the chopped A/D converter can be set in several steps (see **Table 7**). This gives a suitable level for the A/D converter
- After the A/D conversion, a digital low-pass filter reduces the bandwidth (**Table 11**)
- A multiplier amplifies the value depending on the gain (see **Table 9**) and temperature compensation settings
- The offset value is added (see **Table 10**)
- A limiter reduces the resulting signal to 16 bits (see **Chapter 13**) and feeds the Protocol Generation stage

Temperature Compensation

(Details are listed in **Chapter 8**)

- The output signal of the temperature cell is also A/D converted

- The temperature is normalized by subtraction of the reference temperature T_0 value (zero point of the quadratic function)
- The linear path is multiplied with the TC_1 value
- In the quadratic path, the temperature difference to T_0 is squared and multiplied with the TC_2 value
- Both path outputs are added together and multiplied with the Gain value from the EEPROM

6.1 Magnetic Field Ranges

The working range of the magnetic field defines the input range of the A/D converter. It is always symmetrical around the zero field point. Any two points in the magnetic field range can be selected to be the end points of the output value. The output value is represented within the range between the two points.

In the case of fields higher than the range values, the output signal may be distorted. The range must be set before the calibration of offset and gain.

Table 7 Range Setting

Range	Range in mT[1)]	Parameter R
Low	± 50	3
Mid	± 100	1[2)]
High	± 200	0

1) Ranges do not have a guaranteed absolute accuracy. The temperature pre-calibration is performed in the mid range (100 mT)

2) Setting R = 2 is not used, internally changed to R = 1

Table 8 Range

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Register size	R	2		bit	

6.2 Gain Setting

The overall sensitivity is defined by the range and the gain setting. The output of the ADC is multiplied with the Gain value.

Table 9 Gain

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Register size	G	15		bit	Unsigned integer value
Gain range	$Gain$	- 4.0	3.9998	-	1)2)
Gain quantization steps	$\Delta Gain$	244.14		ppm	Corresponds to $1/4096$

1) For Gain values between - 0.5 and + 0.5, the numerical accuracy decreases
To obtain a flatter output curve, it is advisable to select a higher range setting

2) A gain value of +1.0 corresponds to typical 32 LSB_{12}/mT sensitivity (100 mT range, not guaranteed). It is crucial to do a final calibration of each IC within the application using the Gain/OUT_{OS} value

The Gain value can be calculated by

$$Gain = \frac{(G - 16384)}{4096}$$

6.3 Offset Setting

The offset value corresponds to an output value with zero field at the sensor.

Table 10 Offset

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Register size	OS	15		bit	Unsigned integer value
Offset range	OUT_{OS}	-16384	16383	LSB_{12}	1)
Offset quantization steps	ΔOUT_{OS}	1		LSB_{12}	

1) Infineon pre-calibrates the samples at zero field to 50% output value (100 mT range), but does not guarantee the value. Therefore it is crucial to do a final calibration of each IC within the application

The offset value can be calculated by:

$$OUT_{OS} = OS - 16384$$

6.4 DSP Input Low-Pass Filter

A digital low-pass filter is placed between the Hall A/D converter and the DSP, and can be used to reduce the noise level. The low-pass filter has a constant DC amplification of 0 dB (Gain of 1), which means that its setting has no influence on the internal Hall ADC value.

The bandwidth can be set to any of 8 values.

Table 11 Low Pass Filter Setting

Note: Parameter LP	**Cutoff frequency in Hz (-3dB point)[1)]**
0	80
1	240
2	440
3	640
4	860
5	1100
6	1390
7	off

1) As this is a digital filter running with an RC-based oscillator, the cutoff frequency may vary within ±20%

Table 12 Low-Pass Filter

Parameter	**Symbol**	**Limit Values**		**Unit**	**Notes**
		min.	**max.**		
Register size	LP		3	bit	
Corner frequency variation	Δf	- 20	+ 20	%	

Note: In range 7 (filter off), the output noise increases.

Figure 7 shows the filter characteristics as a magnitude plot (the highest setting is marked). The “off” position would be a flat 0 dB line. The update rate after the low-pass filter is 16 kHz.

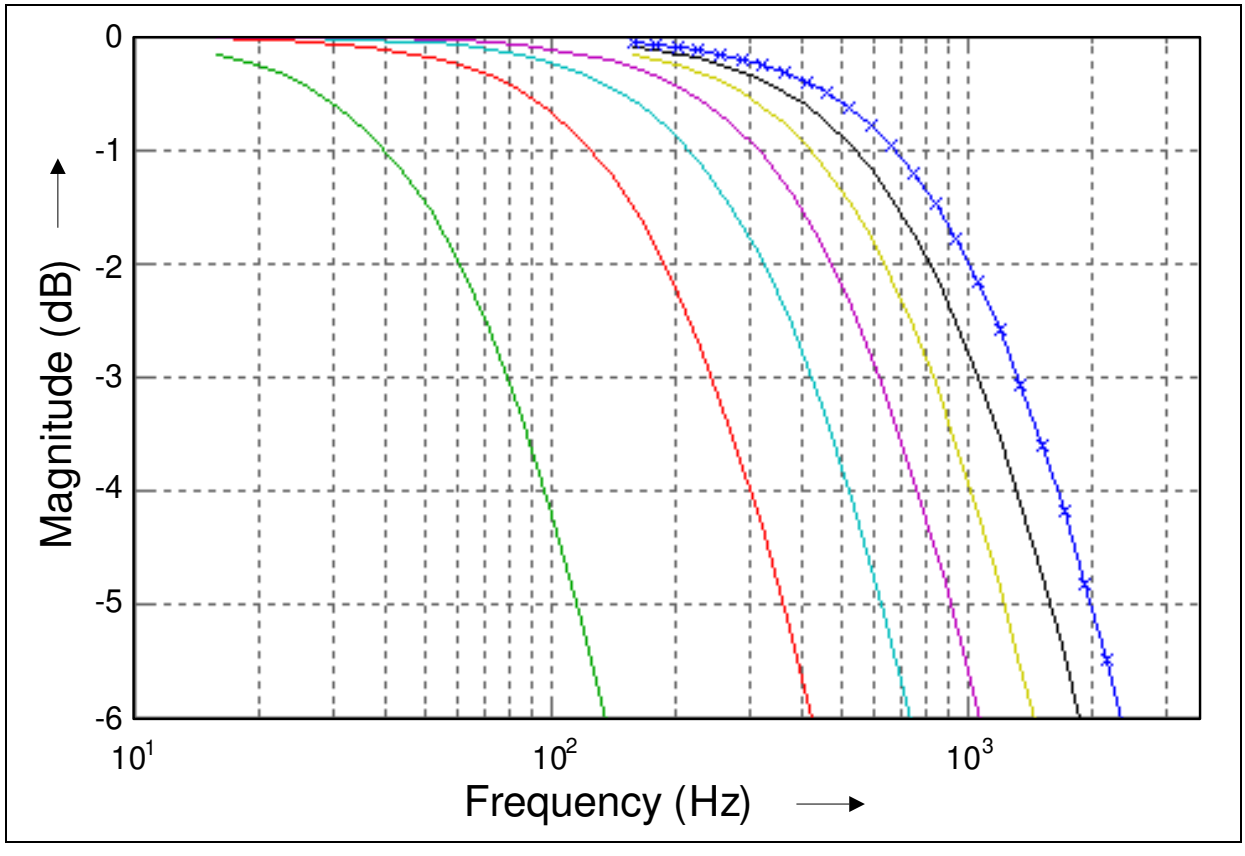


Figure 7 DSP Input Filter (Magnitude Plot)

6.5 Clamping

The clamping function is useful for separating the output range into an operating range and error ranges. If the magnetic field is exceeding the selected measurement range, the output value OUT is limited to the clamping values.

Table 13 Clamping

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Register size	CL, CH	2 x 7		bit	(0...127)
Clamping value low	OUT_{CL}	0	65535	LSB_{16}	1)
Clamping value high	OUT_{CH}	0	65535	LSB_{16}	1) 2)
Clamping quantization steps	ΔOUT_{Cx}	512		LSB_{16}	3)

1) For CL = 0 and CH = 127, the clamping function is disabled

2) $OUT_{CL} < OUT_{CH}$ mandatory

3) Quantization starts for CL at 0 LSB_{16} and for CH at 65535 LSB_{16}

The clamping values are calculated by:

Clamping value low (deactivated if CL=0):

$$OUT_{CL} = CL \cdot 32 \cdot 16$$

Clamping value high (deactivated if CH=127):

$$OUT_{CH} = (CH + 1) \cdot 32 \cdot 16 - 1$$

Figure 8 shows an example in which the magnetic field range between B_{min} and B_{max} is mapped to output values between 10240 LSB_{16} and 55295 LSB_{16}.

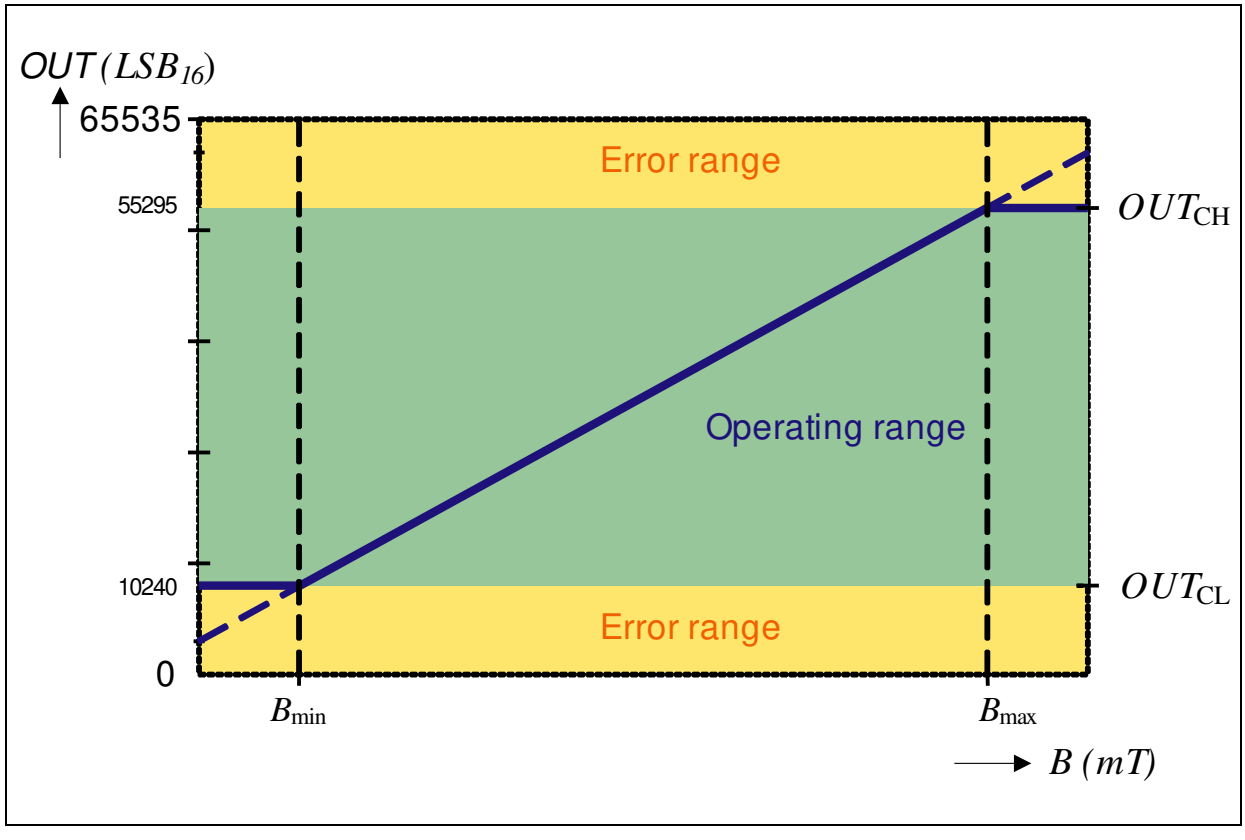


Figure 8 Clamping Example

Note: The clamping high value must be above the low value. If OUT_{CL} is set to a higher value than OUT_{CH}, the OUT_{CH} value is dominating. This would lead to a constant output value independent of the magnetic field strength.

7 Error Detection

Different error cases can be detected by the On-Board Diagnostics (OBD) and reported to the microcontroller in the status nibble (see **Chapter 13**).

7.1 Voltages Outside the Operating Range

The output signals an error condition if V_{DD} crosses the overvoltage threshold level.

Table 14 Overvoltage

Parameter	Symbol	Limit Values			Unit	Notes
		min.	typ.	max.		
Overvoltage threshold	V_{DDov}	16.65	17.5	18.35	V	1)

1) Overvoltage bit activated in status nibble, output stays in “off” state (high ohmic)

7.2 EEPROM Error Correction

The parity method is able to correct a single bit in the EEPROM line. One other single bit error in another EEPROM line can also be detected, but not corrected. In an uncorrectable EEPROM failure, the open drain stage is disabled and kept in the off state permanently (high ohmic/sensor defect).